APPLICA	BLE STAN	IDARD																	
	OPERATING TEMPERATURE RANGE OPERATING HUMIDITY RANGE		-35°C TO +85 °C(N	OTE 1)	STORAGE TEMPERATU	JRE RANGE	-10°C TO +60°C(N	OTE	3)										
RATING			20 % TO 80 % (NOTE 2)		STORAGE HUMIDITY RANGE		40 % TO 70 %(NO		3)										
	VOLTAGE		AC 150 V		APPLICABLE CONNECTOR		DF13-*S-1.25C												
	CURRENT		1 A		APPLICABLE CONTACT		DF13(G)-26303 DF13-3032S												
			SPEC	IFICA	TIONS		DI 13 30320	<u> </u>											
	ГЕМ		TEST METHOD			REC	QUIREMENTS	QT	AT										
	RUCTION	I			I			1 71	1										
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCO	ACCORDING TO DRAWING.			X										
MARKING		CONFIRMED VISUALLY.							X										
		CTERISTICS				1 30 mQ MAY													
CONTACT RESISTANCE INSULATION		100 m A (DC OR 1000 Hz).				30 mΩ MAX. 500 MΩ MIN.			+-										
RESISTANCE					500 IV														
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.			_										
	VICAL CHA							X	1										
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.			② NO	 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			-										
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE			① NO	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 													
SHOCK		490 m/s ²	0.75 mm, AT 2 h, FOR 3 DIRECTIONS. 490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.						-										
FNVIRO	NMENTAL		ACTERISTICS					X											
RAPID CHA			RATURE -55 \rightarrow 5 TO 35 \rightarrow +8	5→ 5 TO 3	5 °C ① CO	NTACT RES	ISTANCE: 30mΩ MAX.	X											
TEMPERATURE		UNDER 5 CYCLES.				(2) INSULATION RESISTANCE: $500~\text{M}\Omega$ MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			_										
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			OF				_										
RESISTANCE TO SOLDERING HEAT		,	1) REFLOW SOLDERING «REFLOW AREA»			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			<u> </u>										
		MAX250°C WITHIN 10 sec			_														
		MIN 230°C WITHIN 60 sec ≪PREHEATING AREA≫ 170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW.																	
		2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.																	
										SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 245±3°C FOR INSERTION DURATION, 3sec.				SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.			_
										REMARKS		I.		., 0000.	1 30 70	<u></u>		X	1
	UDE THE TEMP	PERATURE	RISING BY CURRENT																
NOTE3: APPL	Y TO THE CON		LONG TERM STORAGE FOR U																
	ER MOUNTED (NSPORTATION.	ON PCB B	OARD, OPERATING TEMPERA	ATURE ANI) HUMIDITY R	ANGE IS AF	PPLIED FOR INTERIM STOR	AGE DI	URING										
		RIPTION OF REVISIONS DESIG			NED CHECKED			ATE											
Unless oth	erwise speci	fied, refer	ed, refer to IEC 60512.			APPROVE		_	04.05										
						CHECKE	_												
						DESIGNE	D TS.KUMAZAWA MK.INOUE		04.05										
Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DRAWIN	I		MK.INOUE 18.04.05 ELC-083664-75-00											
HS.	S	PECIF	CATION SHEET	SHEET PAR		NO. DF13-*P-1.25V(75)											
	HIR	HIROSE ELECTRIC CO., LTD.			CODE NO.	DDE NO. CL536		\triangle	1/1										
	i	,				i .													